

Benvenuto in O-Leading

O-Leading si impegna per essere il partner della soluzione one stop nella catena di fornitura EMS, tra cui progettazione PCB, fabbricazione PCB e assemblaggio PCB (PCBA). Forniamo alcune delle tecnologie PCB più avanzate, tra cui PCB HDI, PCB multistrato, PCB rigidi-flessibili Siamo in grado di supportare dal prototipo a rotazione rapida alla produzione media e di massa.

In generale, i nostri clienti globali sono molto colpiti dai nostri servizi: risposta rapida, prezzo competitivo e impegno per la qualità. Fornire un servizio tecnico più prezioso e una soluzione globale è il modo in cui O-leader in avanti.

Guardando al futuro, O-Leading si concentrerà sull'innovazione e sullo sviluppo della tecnologia di produzione elettronica come sempre e farà sforzi costanti sul servizio one-stop PCB e PCBA per fornire servizi di prima classe e creare più valore per i nostri clienti.

Descrizione del prodotto

| | | | |
|-------------------------------------|--|----------------------------|------------------------------|
| Luogo d'origine | Guangdong, Cina (continente) | Marchio | O-leader |
| Materiale di base | FR-4, Alluminio | Spessore di rame | 0,5 once-5 once |
| Min. Dimensione del foro | 0,2 millimetri | Min. Larghezza della linea | 0,2 millimetri |
| Finitura superficiale applicabile a | oro da immersione, OSP, HASL senza piombo | Spessore della scheda | 0.1-5mm |
| certificati | led, cellulare, condizionatori, lavatrici | personaggio | PCB di controllo industriale |
| peso | ISO9001, UL, RoHS, SGS | Q / CTN | 10PCS-100PCS |
| Numero di modello | 0,01 kg -5 kg | MOQ | 10 pezzi |
| colore | produttore pcba assemblaggio pcb banca di potere | Min. Interlinea | 0,2 millimetri |
| tipo desigh | blu, rosso, verde, nero. giallo | prezzo | \$ 0,1- \$ 10 |
| | requisito del cliente | taglia | 0.01m3-10m3 |

16 anni produttore professionale di schede PCB OEM

| articolo | 2014 | | 2015 ~ 2016 | | 2017 ~ 2018 | |
|--|---|-----------|-------------|-----------|-------------|-----------|
| | Volume | Campione | Volume | Campione | Volume | Campione |
| Conteggio dei livelli | 32 | 42 | 38 | 44 | 42 | 48 |
| Linea / spazio min (µm) | 50/50 | 40/45 | 40/45 | 40/40 | 35/40 | 35/35 |
| Foro min diametro (mm) | 0.15 | 0.10 | 0.15 | 0.10 | 0.15 | 0.10 |
| Proporzioni di PTH | 14: 1 | 16: 1 | 16: 1 | 18: 1 | 18: 1 | 20: 1 |
| N + C + N | 4 + C + 4 | 5 + C + 5 | 5 + C + 5 | 6 + C + 6 | 5 + C + 5 | 6 + C + 6 |
| Qualsiasi interconnessione di layer | 5 + 2 + 5 | 6 + 2 + 6 | 5 + 2 + 5 | 6 + 2 + 6 | 5 + 2 + 5 | 6 + 2 + 6 |
| Riempimento della piastra tramite | SÌ | - | SÌ | - | SÌ | - |
| Min. spessore del nucleo (escluso rame) (µm) | 50 | 40 | 40 | 30 | 40 | 30 |
| Min. Diametro del trapano laser (µm) | 75 | 65 | 65 | 50 | 50 | 40 |
| Via sepolto foro / impilati via | Sì | - | Sì | - | Sì | - |
| Materiale | FR4, Megtron, Nelco, Rogers, Heavy Copper, ecc. | | | | | |

| | | | | | | |
|------------------------------|---|---|----|---|----|---|
| PCB condensatore incorporato | Sì | - | Sì | - | Sì | - |
| Processo di superficie | Senza piombo HASL, ENIG, OSP, argento ad immersione, stagno ad immersione, Oro flash, placcatura in oro, placcatura in oro duro selettiva, Maschera saldabile, inchiostro al carbonio | | | | | |



Fornitore di circuiti stampati

La nostra squadra



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



certificazioni

CICC INSPECTION CERTIFICATION



嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE
Certificate No: 18118Q10347R05

We hereby certify that
O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED
Credit No: 61691591-000-07-18-7
Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK
Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial issuance period: February 27, 2018
Renewal date: April 22, 2019
This certificate is valid during: April 22, 2019 – February 26, 2021
This certificate is invalid without CICC qualified label in the following period

| | | |
|-----------------------------|------------------------------|----------------|
| First supervision and audit | Second supervision and audit | Qualified mark |
|-----------------------------|------------------------------|----------------|

The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the state. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The actual information of this certification can be searched on the internet of CICC www.cicc.com.cn by the site of internet www.cicc.com.cn.






CICC INSPECTION CERTIFICATION



嘉泰认证

质量管理体系认证证书
证书号: 18118Q10347R05

兹证明
诚领供应链(香港)有限公司
统一社会信用代码: 61691591-000-07-18-7
注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室
经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

建立的质量管理体系符合
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

认证范围
印刷线路板的销售

初次获证日期: 2018年02月27日
换证日期: 2019年04月22日
证书有效期: 自2019年04月22日至2021年02月26日
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

| | | |
|-------|-------|-----|
| 第一次监审 | 第二次监审 | 黏贴处 |
|-------|-------|-----|

本证书认证范围不包括未取得有效的国家规定的行政许可、资质许可的产品/服务范围; 本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效; 本证书信息可在国家认监委网站: www.cnca.gov.cn及CICC网站www.cicc.com.cn查询。






Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED
1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



Member of the SGS Group (SGS SA)

Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various substances like Cadmium (Cd), Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr(VI)), Sum of PBBs, etc.



Member of the SGS Group (SGS SA)



ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
 ROOM 1205, 12/F
 TAI SANG BANK BLDG
 130-132 DES VOEUS ROAD
 CENTRAL, HONG KONG

E490354

| Type | Cond Width | | | SS/ DS/ DSO | Max | Max | | | Meets UL796 | C T | |
|--|---------------|----------------|----------------------|-------------------|----------------|-------------|-------------|------------|----------------|--------|---|
| | Min | Min | Cond | | Area | Solder | Oper | Flame | | | |
| | mm(in) | Edge mm(in) | Thk mic(mil) | | Diam mm(in) | Limits C | Temp sec | Class C | DSR | I | |
| Multilayer (mass laminate) printed wiring boards. | | | | | | | | | | | |
| O-LEADING-401 | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | DS | 12.7 (0.5) | 260 | 10 | 130 | V-0 | - | - |
| O-LEADING-407 | 0.08 (0.003) | 0.2 (0.008) | 17 (0.67) | DS | 9.7 (0.4) | 260 | 10 | 130 | V-0 | All | - |
| Multilayer printed wiring boards. | | | | | | | | | | | |
| O-LEADING-408 | 0.125 (0.005) | 0.125 (0.005) | 12 (0.47) Int:136 | DS | 50.8 (2.0) | 280 | 20 | 130 | V-0 | All | * |
| Single layer printed wiring boards. | | | | | | | | | | | |
| O-LEADING-002 | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 105 | V-0 | All | - |
| O-LEADING-003 | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 130 | V-0 | ▲ | - |
| O-LEADING-033 | 0.15 (0.006) | 0.3 (0.012) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 10 | 120 | V-0 | All | - |
| O-LEADING-205 | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | DS | 69.6 (2.7) | 260 | 10 | 130 | V-0 | All | - |
| O-LEADING-206 | 0.15 (0.006) | 0.33 (0.013) | 17 (0.67) | DS | 69.6 (2.7) | 260 | 10 | 130 | V-0 | All | - |
| O-LEADING-D01 | 0.14 (0.006) | 0.15 (0.006) | 33 (1.30) | DS | 25.4 (1.0) | 260 | 10 | 130 | V-0 | All | * |
| O-LEADING-S01 | 0.25 (0.010) | 0.25 (0.010) | 17 (0.67) | SS | 25.4 (1.0) | 260 | 4 | 130 | V-0 | All | * |

WIRING, PRINTED - COMPONENT | UL Product iQ

| | | | | | | | | | | | |
|----------------------|--------------|--------------|-----------|----|------------|-----|---|-----|-----|-----|---|
| O-LEADING-S02 | 0.2 (0.008) | 0.2 (0.008) | 17 (0.67) | SS | 25.4 (1.0) | 260 | 4 | 130 | HB | ▲ | * |
| O-LEADING-S03 | 0.25 (0.010) | 0.25 (0.010) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 4 | 130 | V-0 | All | * |

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



| Quick Turn Lead Time | | |
|----------------------|----------|---------------------|
| Layer Count: | Lead Tim | Special Requirement |
| 1L/2L | 2-3days | 24 Hours,48 Hours |
| 4L | 3-4days | 48 Hours |
| 6L | 4-5days | 72 Hours |
| 8L | 5-6days | NA |
| 10L | 6-7days | NA |
| 12L | 7-8days | NA |
| 14L | 8-9days | NA |

| Standard Lead Time | | |
|--------------------|------------------|------------------------|
| Layer Count: | Sample Lead Time | Volume order lead time |
| 2L | 4 days | 10 days |
| 4L | 5 days | 11 days |
| 6L | 6 days | 12 days |
| 8L | 8 days | 14 days |
| 10L | 10 days | 16 days |
| 12L | 12 days | 18 days |
| 14L | 14 days | 20 days |
| 16-32L | 18 days | 24 days |

Capacità di processo

Funzionalità di produzione di PCB

Conteggio strati: 1 strato-32 strati

Spessore rame finito □ 1 / 3oz-12oz

Larghezza min linea / spaziatura interna □ 3.0mil / 3.0mil

Larghezza min linea / spaziatura esterna: 4.0mil / 4.0mil

Rapporto di aspetto massimo: 10: 1

Spessore della scheda □ 0,2 mm-5,0 mm

Dimensione massima del pannello (pollici): 635 * 1500mm

Dimensione minima del foro: 4mil

Tolleranza del foro Plated: +/- 3mil

Blind / Buried Vias (tipi All): Sì

Via Fill (conduttivo, non conduttivo): Sì

Materiale base: FR-4, FR-4hg Tg. Materiale privo di alogeni, Rogers, Base in alluminio,poliimmide,
Rame pesante

Finiture superficiali: HASL, OSP, ENIG, HAL-LF, argento mmmm,Immersion Tin, dita d'oro, inchiostro al carbonio

Capacità di produzione SMT

Materiale PCB: FR-4, CEM-1, CEM-3, scheda a base di alluminio

Dimensione massima PCB: 510x460mm

Dimensioni min PCB: x 50x50mm

Spessore PCB □ 0,5 mm-4,5 mm

Spessore della scheda □ 0,5-4mm

Dimensioni min componenti: 0201

Componente di dimensione del chip standard: 0603 e superiore

Altezza massima componente □ 15mm

Passo minimo di piombo: 0,3 mm

Passo palla BGA min: 0.4mm

Precisione di posizionamento: +/- 0,03 mm